EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	("205"/$.ccls. "204"/$.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) with (bonding with pad) and passivation near5 layer and bump and $5resist and wafer and (hole opening via) and current	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 11:48
S2	48	(electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) with (bonding with pad) and passivation near5 layer and bump and $5resist and wafer and (hole opening via) and current	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 11:36
S3	5	("205"/$.ccls. "204"/$.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) with (bond$3 with pad) and passivation near5 layer and bump and $5resist and wafer and (hole opening via) and current	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 11:53
S4	13	("205"/$.ccls. "204"/$.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) with (bond$3 with pad) and $5resist and wafer and (hole opening via) and current	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 12:00
S5	4	("205"/$.ccls. "204"/$.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) with (bond$3 with pad) and $5resist and (hole opening via) and (((revers$4 forward electrodeposition cathodic pulse period$4) near5 (current step)) ((positive$3 negative$2) near5 (pulse step)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 13:40
S6	120	(electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) with (bond$3 with pad) and $5resist and (hole opening via) and (((revers$4 forward electrodeposition cathodic pulse period$4) near5 (current step)) ((positive$3 negative$2) near5 (pulse step))) not S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 13:38

S7	108	(electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) with (bond$3 with pad) and $5resist and (hole opening via) and (((revers$4 forward electrodeposition cathodic pulse period$4) near5 (current step))) not S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 15:56
S8	0	("205"/104.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) with (bond$3 with pad) and $5resist and (hole opening via)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 13:41
S9	1	("205"/104.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) with (bond$3 with pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 13:41
S10	7	("205"/104.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) with ((bond$3 with pad) bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 13:44
S11	3	("205"/103.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) with ((bond$3 with pad) bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 13:46
S12	5	("205"/102.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) with ((bond$3 with pad) bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 13:48
S13	16	("205"/102.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) with ((bond$3 with pad) bump interconnect)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 13:50
S14	23	("205"/104.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) with ((bond$3 with pad) bump interconnect)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 13:56

S15	12	("205"/105.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) with ((bond$3 with pad) bump interconnect)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 14:42
S16	9	("2951978" | "4906346" | "5352350" | "5443707" | "5958207" | "5985126" | "6074544" | "6159354").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/16 13:58
S17	4	("6409903").URPN.	USPAT	OR	ON	2006/08/16 13:59
S18	237	("205"/$.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) with ((increas$3 with current)) and ((bond$3 with pad) bump interconnect)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 14:43
S19	10	("205"/$.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) with (increas$3 with (current near5 step)) and ((bond$3 with pad) bump interconnect)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 14:44
S20	5	("205"/$.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) with (increas$3 with (current near5 step)) and ((bond$3 with pad) bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 14:47
S21	7	("205"/$.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) and (increas$3 with (current near5 step)) and ((bond$3 with pad) bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 16:15
S22	7	("205"/$.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) and (increas$3 near15 (current near5 step)) and ((bond$3 with pad) bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 14:50
S23	15	("205"/$.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) and (increas$3 near15 (current near5 step)) and (interconnect)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 14:57

S24	129	("205"/$.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) and (increas$3 near15 (current near5 step))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 15:44
S25	8	("3510410" | "3930966" | "4517059" | "4571287" | "4798656").PN. OR ("6113770"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/16 15:02
S26	147	("205"/$.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) and (increas$3 with(current near5 step))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 15:45
S27	147	("205"/$.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) and (increas$3 with (current near5 step))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 15:45
S28	18	("205"/$.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) and (increas$3 with (current near5 step)) not S24	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 15:50
S29	501	(electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) and (increas$3 with (current near5 step)) not S27	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 16:08
S30	53	(electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) with (increas$3 with (current near5 step)) not S27	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 15:51
S31	39	(electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) with (bond$3 with pad) and $5resist and (hole opening via) and (((revers$4 forward electrodeposition cathodic pulse) near5 (current))) not S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 16:03

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S32	7	(electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) with (bond$3 with pad) and $5resist and (hole opening via) and (((revers$4 forward electrodeposition cathodic) near5 (current))) not S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 16:05
S33	8	(electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) with (bond$3 with pad) and $5resist and (hole opening via) and (((revers$4 forward electrodeposition cathodic) near5 (current)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 16:06
S34	22	(electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) with (bond$3 with pad) and (((revers$4 forward cathodic) near5 (current)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 16:06
S35	100	(electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) and (increas$3 with (current near5 step)) and ((bond$3 with pad) bump interconnect)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 16:09
S36	77	("205"/$.ccls.) and (electrolysis electrolytic electrochemic$4 plating electrodeposit$5 electroplat$5) and (pulse with (current)) and ((bond$3 with pad) bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 16:16